

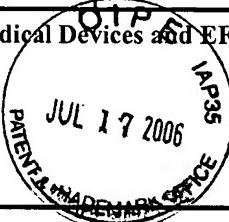
**TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT**  
**(Under 37 CFR 1.97(b) or 1.97(c))**

Docket No.  
P-US083-A-MG

In Re Application of: Adam L. Cohen

Application No.	Filing Date	Examiner	Customer No.	Group Art Unit	Confirmation No.
10/697,598	October 29, 2003	Stewart, Alvin J.	32107	3738	

Title: Medical Devices and EFAB Methods and Apparatus for Producing Them



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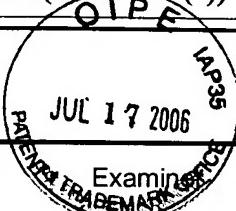
Dated: July 13, 2006

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Address to:  
**Commissioner for Patents**  
P.O. Box 1450  
Alexandria, VA 22313-1450

**37 CFR 1.97(b)**

1.  The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.

**37 CFR 1.97(c)**

2.  The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:

the statement specified in 37 CFR 1.97(e);

**OR**

the fee set forth in 37 CFR 1.17(p).

## INFORMATION DISCLOSURE CITATION

ATTY DOCKET NO. P-US083-A-MG	APPLICATION NO. 10/697,598
APPLICANT(S) Adam L. Cohen	
FILING DATE October 29, 2003	GROUP ART UNIT 3738

JUL 17 2006

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
1	5,190,637	03/02/1993	Henry Guckel	205	118	
2	5,378,583	01/03/1995	Guckel, et al.	430	325	
3	5,496,668	03/05/1996	Guckel, et al.	430	9	
4	5,576,147	11/19/1996	Guckel, et al.	430	313	
5	5,718,618	02/17/1998	Guckel, et al.	451	41	
6	5,866,281	02/02/1999	Guckel, et al.	430	22	
7	5,908,719	06/01/1999	Guckel, et al.	430	5	
8	6,027,630	02/22/2000	Adam L. Cohen	205	135	

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

9	Cohen, et al., "EFAB: Batch Production of Functional, Fully-Dense Metal Parts with Micron-Scale Features", Proc. 9th Solid Freeform Fabrication, The University of Texas at Austin, August 1998, pg. 161.
10	Adam L. Cohen, et al., "EFAB: Rapid, Low-Cost Desktop Micromachining of High Aspect Ratio True 3-D MEMS", Proc. 12th IEEE Micro Electro Mechanical Systems Workshop, IEEE, Jan 1999, pg. 244.
11	"Microfabrication - Rapid Prototyping's Killer Application", Rapid Prototyping Report, CAD/CAM Publishing, Inc., June 1999, pgs. 1-5.
12	Adam L. Cohen, "3-D Micromachining by Electrochemical Fabrication", Micromachine Devices, March 1999, pgs. 6-7.
13	Gang Zhang, et al., "EFAB: Rapid Desktop Manufacturing of True 3-D Microstructures", Proc. 2nd International Conference on Integrated MicroNanotechnology for Space Applications, The Aerospace Co., April 1999.
14	F. Tseng, et al., "EFAB: High Aspect Ratio, Arbitrary 3-D Metal Microstructures Using a Low-Cost Automated Batch Process", 3rd International Workshop on High Aspect Ratio Microstructure Technology (HARMST'99), June 1999.
15	Adam L. Cohen, et al., "EFAB: Low-Cost, Automated Electrochemical Batch Fabrication of Arbitrary 3-D Microstructures", Micromachining and Microfabrication Process Technology, SPIE 1999 Symposium on Micromachining and Microfabrication, September 1999.
16	F. Tseng, et al., "EFAB: High Aspect Ratio, Arbitrary 3-D Metal Microstructures Using a Low-Cost Automated Batch Process", MEMS Symposium, ASME 1999 International Mechanical Engineering Congress and Exposition, November, 1999.
17	Adam L. Cohen, "Electrochemical Fabrication (EFABTM)", Chapter 19 of the MEMS Handbook, edited by Mohamed Gad-El-Hak, CRC Press, 2002, pgs. 19/1 - 19/23.

EXAMINER:

DATE CONSIDERED:

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.